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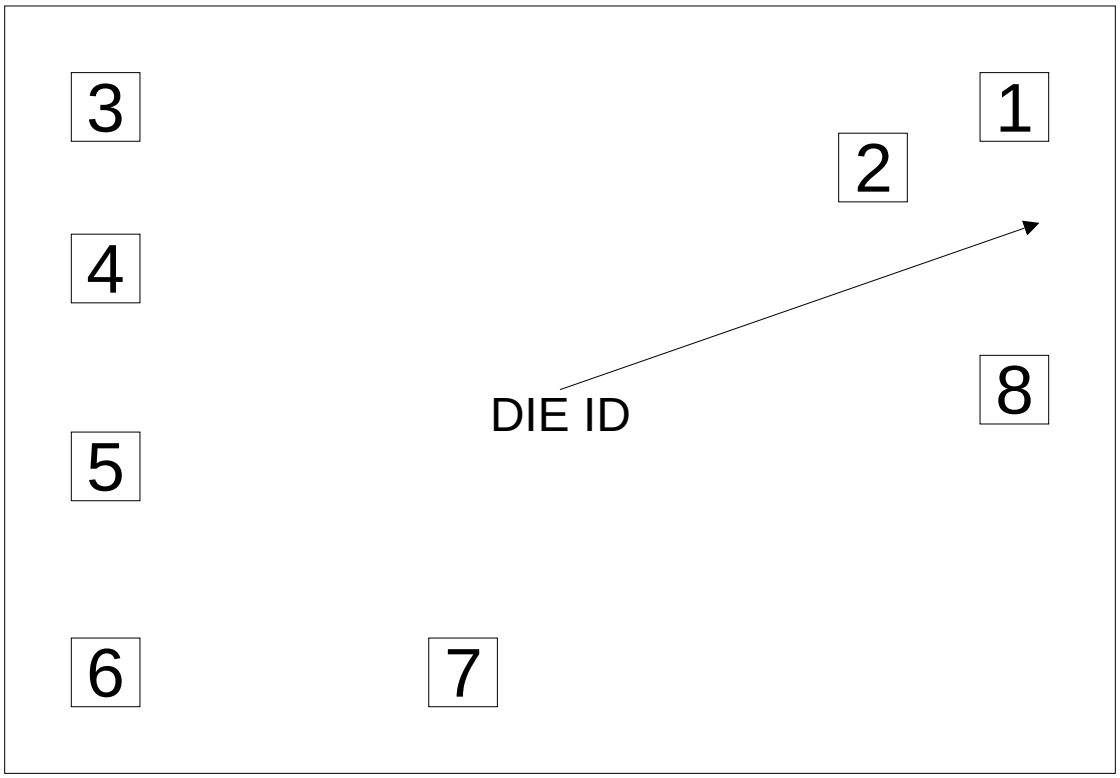
LM160 MD8
High Speed Differential Comparator

JAN 21, 2010

DIE LAYOUT (E-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM160E	Bond Pad Opening Size (min)	86.36µm x 86.36µm
Die Step	E	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1397.0µm x 965.2µm 55.0mils x 38.0mils	Back Side Connection	Floating or -VCC
Thickness	304.8µm Nominal		
Min Pitch	259.08µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(E-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
INPUT 2	1	572	356	86	x	86
INPUT 1	2	394	279	86	x	86
V-	3	-572	356	86	x	86
NC	4	-572	152	86	x	86
GND	5	-572	-97	86	x	86
OUTPUT 2	6	-572	-356	86	x	86
OUTPUT 1	7	-122	-356	86	x	86
V+	8	572	0	86	x	86

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Notes

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